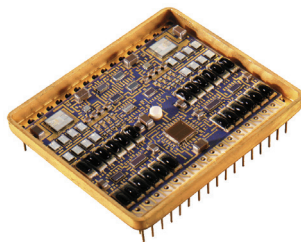
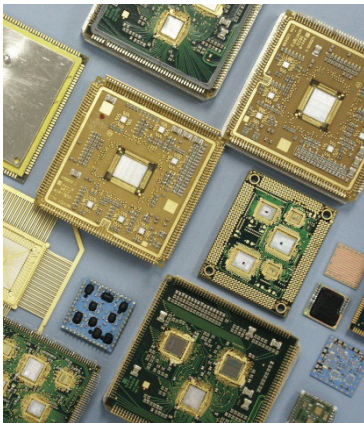


# Microelectronics

Cutting edge technology meeting demands of a constantly evolving industry

	Microelectronics Assembly	Ceramic Substrates	Passive and Active Components	Design and Test Solutions
<b>Overview</b>	<ul style="list-style-type: none"> <li>• Assembly of very small microscopic electronic components into microelectronic assemblies. This includes microwave electronic assemblies used in mission critical satellite and defense, and medical applications.</li> </ul>	<ul style="list-style-type: none"> <li>• Manufacture of advanced components and packages, providing solutions for high interconnect density, compact networks and high-frequency applications.</li> </ul>	<ul style="list-style-type: none"> <li>• Design, manufacture and assembly of radio frequency components.</li> </ul>	<ul style="list-style-type: none"> <li>• Design and Development of High Density Interconnect Modules, PCBA's and Box build assemblies.</li> <li>• Automated Test Development for electronic assemblies including microwave modules.</li> </ul>
<b>Capabilities</b>	<ul style="list-style-type: none"> <li>• Wafer &amp; die processing, monolithic packaging and custom microelectronic packaging</li> <li>• Automated ball, ribbon, and wedge bonding</li> <li>• Multi-chip packaging</li> <li>• Both automated &amp; manual epoxy &amp; eutectic attachment including GaN and GaAs die</li> <li>• Encapsulation utilizing dam and fill</li> <li>• Hermetic package seal utilizing seam sealing or laser welding</li> <li>• RF tuning</li> <li>• Precision and proprietary fully hands-free, automated manufacturing.</li> <li>• Chip-on-board, multi-chip technology, flip chip, die stacking and mixed technology devices.</li> </ul>	<ul style="list-style-type: none"> <li>• High-Density Multilayer LTCC solutions</li> <li>• Precision Thick-Film Substrates</li> <li>• High-Frequency Etched Thick-Film Substrates</li> <li>• AlN substrates</li> <li>• BeO substrates</li> <li>• Plating</li> <li>• Automated manufacturing</li> </ul>	<ul style="list-style-type: none"> <li>• RF Filters               <ul style="list-style-type: none"> <li>- Low pass, bandpass</li> <li>- Tunable</li> <li>- Waveguide, coaxial, ceramic</li> </ul> </li> <li>• Multiplexers / Duplexers</li> <li>• Attenuators</li> <li>• Isolators &amp; circulators</li> <li>• Frequency multipliers &amp; dividers</li> <li>• Power dividers &amp; combiners</li> <li>• Oscillators</li> <li>• Detectors &amp; Mixers</li> </ul>	<ul style="list-style-type: none"> <li>• Design and analysis of electronic assemblies using state-of-the-art software including Cadence layout and analysis tools, HFSS, AWR, SiWave, SolidWorks etc.</li> <li>• Analysis – DC, RF and Signal Integrity. Mechanical and Thermal.</li> <li>• Development of automated high speed testers (up to Ka band) using the LabView programming environment.</li> <li>• Valor DFM Software, integrated with the layout tools, validates the design prior to manufacturing.</li> <li>• Mature product enhancement and redesign.</li> </ul>



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